

Part Number: **HD0x-p**
Weight (mg): 125

p = package designator See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Si	7440-21-3	96.50%	2.60	3.25	965000	25090
		PbO	1317-36-8	2.50%			25000	650
		Ni	7440-02-0	1.00%			10000	260
Solder Paste	RoHS Exempt High Temperature	Pb	7439-92-1	92.50%	9.00	11.25	925000	83250
		Sn	7440-31-5	5.00%			50000	4500
		Ag	7440-22-4	2.50%			25000	2250
Leadframe & Clip	Copper Alloy	Cu	7440-50-8	99.95%	32.15	40.19	999500	321359
		Zn	7440-66-6	0.01%			60	19
		Fe	7439-89-6	0.01%			100	32
		P	7723-14-0	0.03%			340	109
Encapsulation	Epoxy	Silica (SiO2)	14808-60-7	75.50%	55.25	69.06	755000	417122
		Epoxy Resin	Trade secret	14.50%			145000	80110
		Phenol Resin	Trade secret	6.50%			65000	35911
		Brominated Epoxy Resin	Trade secret	2.25%			22500	12431
		Carbon Black	1333-86-4	0.35%			3500	1934
		Sb2O3	1309-64-4	0.50%			5000	2762
		Others	N/A	0.40%			4000	2210
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	1.00	1.25	1000000	10000
				Total	100.00	125.00		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, [Material Composition Declaration for Electronic Products](#).

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

- | | |
|--|---|
| Asbestos | Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Hexavalent chromium compounds | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Lead and lead compounds | Radioactive Substances |
| Mercury and mercury compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Organic tin compounds | Tributyl Tin Oxide (TBTO) |

RoHS Exemptions 5 for Pb in Glass and 7a for Pb in High Temperature, High %Pb in Solder are applied